



## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

ATTORNEY DOCKET NO.: AGX-37

GAV-2823

In re Application: Shooshtarian, et al.

Group Art Unit: 2823

Serial No.: 09/527,873

Examiner: Hsein-Ming Lee

Filed: March 17, 2000

Our Account No.: 04-1403

Confirmation No.: 4182

Title: LOCALIZED HEATING AND COOLING OF  
SUBSTRATES

Commissioner for Patents  
U.S. Patent and Trademark Office  
Washington, DC 20231

**AMENDMENT**

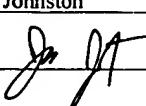
This is a AMENDMENT in the above-identified application and includes the herewith attachment of same date and subject which is incorporated hereinto by reference and the signature below is to be treated as the signature to the attachment in absence of a signature thereto.

Fee requirements (if any) have been calculated as shown below:

Claims remaining after amendment	Highest number previously paid for	Present Extra	Additional Fee
Total Effective Claims	minus	=	x \$18 =
Independent Claims	minus	=	x \$80 =
If amendment enters <u>proper</u> multiple dependent claim(s) into this application for <u>first</u> time, add \$270.00 (per application)			
Since Official Action set an <u>original</u> due date of _____			
PETITION is hereby made for an extension to cover the date this response is filed for which the requisite fee is enclosed (1 month \$110; 2 months \$390; 3 months \$890; 4 months \$1390)			
If Terminal Disclaimer enclosed, add Rule 20(d) Official Fee (\$110.00)			
<b>SUBTOTAL:</b>			\$ _____
If "small entity" verified statement filed [ ] previously, [ ] herewith, enter one-half (½) of subtotal and subtract			
<b>TOTAL:</b>			\$ _____
Other: <u>Information Disclosure Statement List with References &amp; Information Disclosure Statement Cover Sheet; and fee; Letter of Disclosure</u>			\$180.00
<b>TOTAL FEE ENCLOSED:</b>			\$180.00

The Commissioner is hereby authorized to charge any fee specifically authorized hereafter, or any fees in addition to the fee(s) filed, or asserted to be filed, or which should have been filed herewith or concerning any paper filed hereafter, and which may be required under Rules 16-18 (deficiency only) now or hereafter relative to this application and the resulting official document under Rule 20, or credit any overpayment, to our Account No. shown in the heading hereof for which purpose a duplicate copy of this sheet is attached. This statement does not authorize charge of the issue fee in this case.

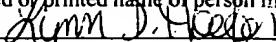
ADDRESS:  
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DORITY & MANNING  
ATTORNEYS AT LAW, P.A.  
By Atty: Jason W. Johnston Reg. No.: 45,675  
Signature: 

I hereby certify that this correspondence and any referenced attachment and fee are being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, U.S. Patent and Trademark Office, Washington, DC 20231, on April 18, 2001.

Lynn D. Hoefer

(Typed or printed name of person mailing paper or fee)



(Signature of person mailing paper or fee)



PATENT  
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Commissioner for Patents  
Washington, D.C. 20231

11/B  
F. Jones  
5-1-01

AMENDMENT

Dear Sir:

In response to the Office Action dated February 14, 2001, please amend the  
above-captioned application as follows:

IN THE CLAIMS:

Please cancel claim 3.

Please amend claims 1, 4-5, 11, and 13 to read as follows (See also Appendix

A):

1. (Amended) A method for heat treating a semiconductor wafer, said method  
comprising the steps of:  
placing a semiconductor wafer in a thermal processing chamber, said  
semiconductor wafer defining a plurality of localized regions along a radial axis;

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